

ABSTRACT OF THE DISCLOSURE

The invention relates to a method for vacuum deposition of circuitry onto a thermoplastic material. In one of its aspects, the invention relates to a vacuum deposition of circuitry for automotive applications. In another of its aspects, the invention relates to a vehicular lamp housing incorporating a circuit placed thereon by vacuum deposition. In
5 another of its aspects, the invention relates to a vehicular lamp housing with vacuum deposition of circuitry powering light-emitting diodes. In another of its aspects, the invention relates to a vehicular lamp housing with a vacuum deposition of circuitry powering removable incandescent lamps.

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